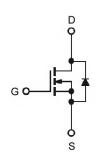


N-Channel 100-V (D-S) MOSFET

Description

The device is using trench DMOS technology. This advanced technology has been especially tailored to minimize R_{DS(ON)}, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Graphic Symbol



Features

- $R_{DS(ON)} = 2.3 \text{m}\Omega @ V_{GS} = 10V$
- Fast switching
- Improve dv/dt Capability
- 100% EAS Guaranteed
- Green Device Available

Typical Applications

- Networking
- Load Switch
- Synchronous Rectifier
- BMS Applications

Package type: TO-263

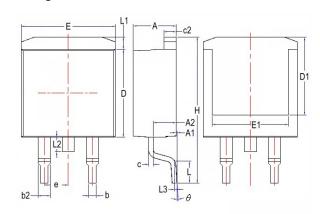
Packing & Order Information

800/Reel



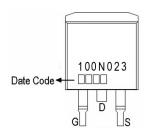
RoHS Compliant

Package Dimension



REF.	Millimeter		REF.	Millimeter		
	Min.	Max.	NEF.	Min.	Max.	
Α	4.37	4.77	Е	9.80	10.36	
A1	0.00	0.25	E1	7.06	-	
A2	2.20	2.80	е	2.54 BSC		
b	0.70	0.96	н	14.70	15.70	
b2	1.17	1.47	L	2.00	2.60	
С	0.30	0.60	L1	1.07	1.47	
c2	1.22	1.42	L2	1.40	1.75	
D	8.50	9.30	L3	0.25 BSC		
D1	6.60	-	θ	0°	9°	

Marking





N-Channel 100-V (D-S) MOSFET

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings					
Symbol	Parameter	Value	Units		
V_{DS}	Drain-Source Voltage	100	V		
V _G S	Gate-Source Voltage	±20	V		
	Continuous Drain Current¹ (Tc =25°C)	250	Α		
l _D	Continuous Drain Current¹ (T _C =100°C)	158	Α		
I _{DM}	Pulsed Drain Current ^{1,2}	1000	Α		
I _{AS}	Single Pulse Avalanche Current, L =0.1mH ³	137	Α		
E _{AS}	Single Pulse Avalanche Energy, L =0.1mH³	938	mJ		
Б	Power Dissipation ⁴ (T _C =25°C)	278	W		
P _D	Power Dissipation ⁴ (T _A =25°C)	2	W		
TJ/T _{STG}	Operating Junction and Storage Temperature	-50 to +150	°C		

Thermal Resistance Ratings					
Symbol	Parameter	Maximum	Units		
$R_{\theta JA}$	Maximum Junction-to-Ambient ¹	62.5	°C/W		
R _θ JC	Maximum Junction-to-Case ¹	0.45	°C/W		

Electrical Characteristics (T _J =25°C unless otherwise specified)							
Symbol	Parameter	arameter Test Conditions		Тур.	Max.	Units	
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	2	2.5	4	V	
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100	-	-	V	
g fs	Forward Transconductance	V _{DS} =10V, I _D =3A	-	20	-	S	
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =20V	-	-	100	nA	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =100V, V _{GS} =0V, T _J =25°C V _{DS} =80V, V _{GS} =0V, T _J =85°C	-	-	1 10	μA	
R _{DS (on)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =40A	-	1.9	2.3	mΩ	
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =50V, L =0.1mH, I _{AS} =60A	180	-	-	mJ	
V _{SD}	Diode Forward Voltage ²	I _S =1A, V _{GS} =0V, T _J =25°C	-	-	1	V	
Is	Continuous Source Current ^{1,6}	V V 0V 5 0	-	-	250		
Ism	Pulsed Source Current ^{2,6}	V _G =V _D =0V, Force Current	-	-	500	Α	

Notes

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
- 3. The EAS data shows maximum rating. The test condition is V_{DD} =50V, V_{GS} =10V, L=0.1mH, I_{AS} =60A.
- 4. The power dissipation is limited by 150 $^{\circ}\mathrm{C}\,$ junction temperature.
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.



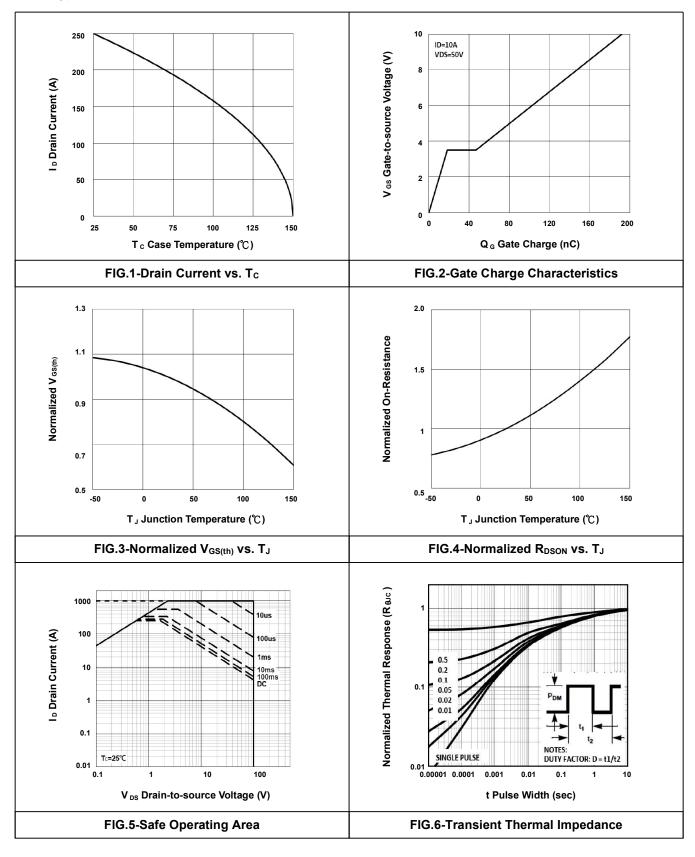
N-Channel 100-V (D-S) MOSFET

Dynamic						
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Qg	Total Gate Charge ²	V _{DS} =50V		192		
Qgs	Gate-Source Charge	I _D =100A		18.5		nC
Qgd	Gate-Drain Charge	V _{GS} =10V		28.3		
td(on)	Turn-On Delay Time ²	V _{DS} =50V		20.6		
tr	Rise Time	I _D =100A		19.8		
td(off)	Turn-Off Delay Time	V _{GS} =10V		66		ns
tf	Fall Time	$R_G = 3.3\Omega$		117		
Ciss	Input Capacitance	V _{DS} =50V		10100		
Coss	Output Capacitance	V _{GS} =0V		2020		pF
Crss	Reverse Transfer Capacitance	f=1.0MHz		53		
Rg	Gate Resistance	V _{GS} =V _{DS} =0V, f =1.0MHz		1.1		Ω



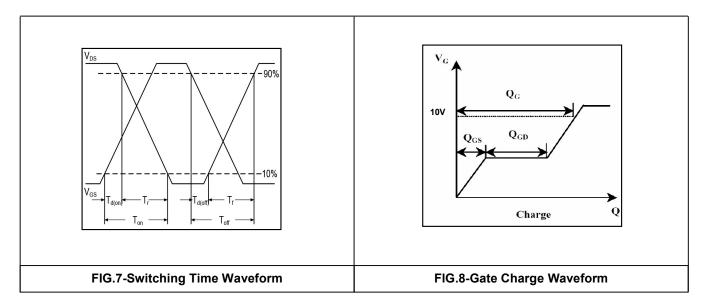
N-Channel 100-V (D-S) MOSFET

• Typical Electrical Characteristics





N-Channel 100-V (D-S) MOSFET





N-Channel 100-V (D-S) MOSFET

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